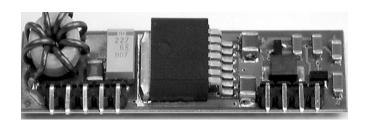


# 5V to 3.3V, AND PROGRAMMABLE DC/DC CONVERTER WITH PARALLELABLE BOOST MODULES

# 6-PAK



#### **FEATURES**

- Small SIP Design
- Parallelable Boost SIP

One stocking part meets a variety of loads

Programmable Control SIP

Control/Boost Pair extremely configurable

Fast Transient Response

No need for large external capacitors Extremely small footprint

Low Component Count

Low cost, high reliability

Staked Pins

Wave solderable

Integrated Input Filter

Low input ripple

#### APPLICATION NOTE

DCAN-34 - 6-PAK Demo Board

Downloadable from our website - cdpowerelectronics.com

#### DESCRIPTION

The 6-PAK™ is a modular system of control and boost SIPs. Each 6A control SIP can also drive up to 8 additional 6A boost SIPs in parallel, for a total of 54A. Each SIP accepts a regulated 5V input (±10%) and provides 1.8V to 3.6Vdc output. The circuit is optimized for high efficiency and fast load transient response needed by telecom, DSP and microprocessor applications.

Advanced thermal design, monolithic power circuitry and synchronous rectification result in outstanding performance and value. With integrated input filter and output capacitors, the 6-PAK system makes a complete power supply which requires no external components over the specified operating range. Pins are staked for wave solderability.

More product information and application notes are available on our website at www.cdpowerelectronics.com

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# **Electrical Specifications**

Unless otherwise specified, operating conditions are as follows:  $V_{in}=5V$ ,  $V_{o}=3.3V$ ,  $I_{o}=6A$ ,  $T_{A}=25$ °C,  $C_{in}=100\mu F$ ,  $C_{o}=\mu F$ .

Parameter		Conditions	Min	Тур	Max	Units
Input						
Input Voltage	$V_{\text{in}}$		4.5	5.0	5.5	V <sub>DC</sub>
Input Current Ripple				200		<b>mA</b> RMS
Required Capacitance	$C_{in}$	Note 1	0	100		μF
Output						
Output Voltage	Vo	Nominal	3.25	3.3	3.35	$V_{ extsf{DC}}$
Output Program Range		Note 2	1.8		3.6	V <sub>DC</sub>
Output Current	lo	T <sub>A</sub> =25°C	0		6	Amps
Output Ripple		20Mhz BW			50	mVp-p
Output Rise Time	Tr			12		μS
Output Capacitance Range	Co		0		5000	μF
Line Regulation				<u>+</u> 0.5		%
Load Regulation		l₀ min - l₀ max		<u>+</u> 0.5		%
Temperature Coefficient	Tc			0.01		%/°C
Combined Variation		V <sub>in</sub> min-max &/or I₀ min-max				
		T <sub>A</sub> =25°C- 85°C	-2		+2	%
Protection		Note 3				
General						
Switching Frequency				800		kHz
Dynamic Response						
$\Delta I_0/\Delta t = 1A/10\mu \text{ sec, } V_i = 5.0V, T_A = 25^{\circ}\text{C}$						
Load Change from Io = 0% to Io = 100%  Peak Deviation				60		mV
Settling time (Vo<10% Peak Deviation)				150		μsec
Load change from Io = 100% to Io = 0%  Peak Deviation				90		mV
Settling time (Vo<10% Pea	k Deviation)			100		μsec
Coming mile (VOC10781 ea	Deviation)			100		μυσο
Temperature						
Operating Temperature			Note 4		+60	°C
Storage Temperature			-40		+125	°C

#### **Notes**

- 1. Input source<3" from 6-PAK™, load transient <3A per SIP. 100μF low ESR capacitor for load transients >3A per SIP.
- 2. Optional programming 1.8 3.6 or  $\pm 10\%$  available. See Table.
- 3. Short circuit and thermal protection.
- 4. 100 lfm air, V₀=3.3V, I₀=6A. See Thermal Design Guide for other conditions.

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## **Programming**

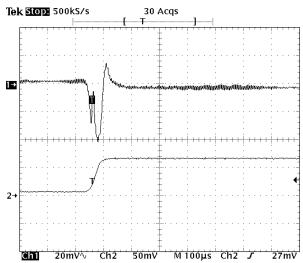
The 6-PAK<sup>TM</sup> is programmed through the Control SIP. All connected Power Boosters follow the Control SIP programming. To program the 6-PAK<sup>TM</sup> for  $V_{out}$ <3.3, connect a resistor across the TRIM and  $V_{o}$  pins. For  $V_{out}$ >3.3, resistor is connected across TRIM and GND.

Table 2

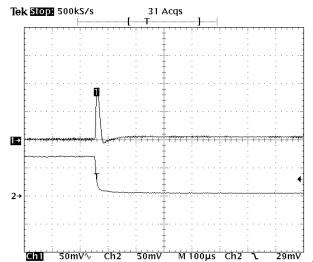
Vout	Resistor Value	$V_{\text{out}}$	Resistor Value
1.8	0Ω	2.8	442Ω
1.9	15.6Ω	2.9	$604\Omega$
2.0	$34\Omega$	3.0	$866\Omega$
2.1	$55.6\Omega$	3.1	1.37k
2.2	$\Omega$ 0.08	3.2	2.80k
2.3	110Ω	3.3	Open
2.4	147Ω	3.4	2.32k
2.5	196Ω	3.5	1.00k
2.6	$255\Omega$	3.6	$649\Omega$
2.7	332Ω		

#### **Transient Response**

Operating conditions are as follows: Vin=5V, Vo=3.3V, Load change from Io=0% to Io=100%, TA=25°C, Cin=0F, Co= $\mu$ F.



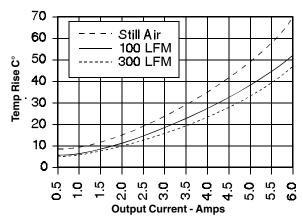
Operating conditions are as follows: Vin=5V, Vo=3.3V, Load change from Io=100% to Io=0%, TA=25°C, Cin=0F, Co= $\mu$ F.



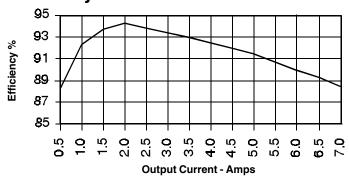
# **Thermal Design Guide**

Locate your operating current, read the junction temp rise from the graph and add to your maximum ambient. 135°C is the maximum allowable operating junction temperature. Test conditions: Device soldered into 4" X 4: PCB, 2-sided with power and ground planes for heat conduction. Due to the difficulty in predicting the thermal effects of airflow velocity and direction, and thermal conduction through ground planes, it is important that the 6-PAK™ be evaluated thermally in each application. For high ambient temperature/high current application, please request our Application Note, "Accurate Measurements of 6-PAK™ Junction Temperature."

Tj Rise vs. lo (Junction Temp Rise vs. Output Current)

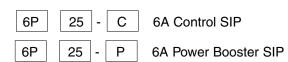


## **Efficiency**



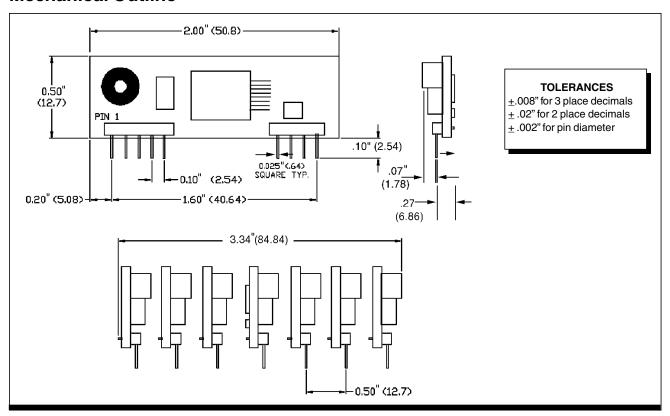
# **Ordering Information**

Typical examples:



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#### **Mechanical Outline**



#### Pin Out

Pin	Function	Description		
1	Vo	Output Voltage		
2	Vo	Output Voltage		
3	TRIM	Output Adjust*		
4	GND	Ground		
5	INTI	InterModule 1		
6	Gnd	Ground		
7	INT2	InterModule 2		
8	Vi	5V Input Voltage		
9	Vi	5V Input Voltage		

<sup>\*</sup> not connected on Boosters

# **System Interconnection Guidelines**

- Each SIP must have input, ground and output pins sunk into common input ground and output planes in the host PC board.
- Two additional common signal traces are required to interconnect INT1 and INT2 pins. These traces must be a least 0.06" wide and make a straight connection among the modules.
- Power Booster SIP must be adjacent to the Control SIP located in the center of the layout, as shown in the Typical Example figure. Recommended distance between SIP pin centers is 0.5".

Standard Options are shown, consult factory for other available options.

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